AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (canceled)

2. (previously presented): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of said ground plate as said signal line;

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole is only directly electrically connected to said ground plate,

wherein an aperture size of said through hole is smaller than a width of said signal line.

Claims 3 and 4 (canceled).

5. (previously presented): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of said ground plate as said signal line;

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole which is formed in said signal line is only directly electrically connected to said signal line, and

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole which is formed in said ground plate is only directly electrically connected to said ground plate.

Claims 6-8 (canceled)

9. (previously presented): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of said ground plate as said signal line;

wherein, a plurality of slit holes are formed by forming said signal line of a plurality of thin strips and by connecting the thin strips at respective terminal ends of the thin strips, and an inner wall of said plurality of slit holes is only directly electrically connected to said signal line,

wherein a width of each of the slit holes is smaller than a width of the signal line.

10. (previously presented): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of the ground plate as said signal line;

wherein a plurality of through holes are formed in said signal line and an inner wall of said plurality of through holes is directly electrically connected to said signal line, and

wherein, said plurality of through holes are formed along a longitudinal direction of a signal transmission line and arranged at equal spaces or in a same pattern.

11. (previously presented): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of the ground plate as said signal line;

wherein a plurality of through holes are formed in said ground plate and an inner wall of said plurality of through holes is directly electrically connected to said ground plate,

wherein, said plurality of through holes are formed along a longitudinal direction of a signal transmission line and arranged at equal spaces or in a same pattern, and

wherein an aperture size of each of said plurality of through holes is smaller than a width of said signal line.

12. (canceled)

13. (previously presented) The semiconductor integrated circuit according to claim 5, wherein an aperture size of said through hole formed in said signal line and an aperture size of said through hole formed in said ground plate is smaller than a width of said signal line.

14. (previously presented) The semiconductor integrated circuit according to claim 10, wherein an aperture size of each of said plurality of through holes is smaller than a width of said signal line.

15. (previously presented) The semiconductor integrated circuit according to claim 9, wherein a width of each of the slit holes is smaller than a width of each of the respective plurality of thin strips.

16. (new): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of said ground plate as said signal line;

wherein at least two through holes are formed in said signal line, and inner walls of said through holes are only directly electrically connected to said signal line,

wherein an aperture size of each of said at least two through holes is smaller than a width of said signal line.

17. (new): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed on an opposite side of said ground plate as said signal line;

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole is only directly electrically connected to said signal line,

wherein an aperture size of said through hole is smaller than a width of said signal line, and

wherein a width of said signal line, where said through hole is formed, is the same as a width of said signal line where said through hole is not formed.